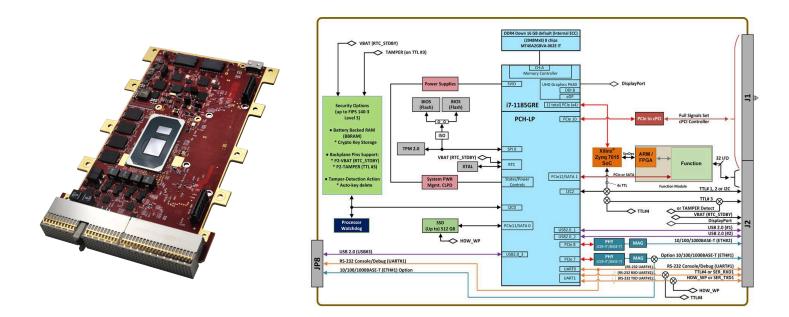


# 75INT6 3U cPCI Single Board Computers

3U cPCI System Controller Single Board Computer Intel® Core™ i7-1185GRE Processor (Tiger Lake) w/ 4 Cores, to 2.8 GHz

The 75INT6 is a 3U Compact PCI (cPCI) System Controller Intel® Core™ i7-1185GRE Processor / integrated PCH-LP (Tiger Lake) w/ 4 Cores & 12M Smart Cache running up to 2.8 GHz SBC board which can be configured with one smart I/O and communications function module. Ideally suited for rugged Mil-Aero applications, the 75INT6 delivers off-the-shelf solutions that accelerate deployment of SWaP-optimized systems in air, land, and sea applications.



#### **Features**

- Compact PCI (cPCI) Full System Controller
- Intel® Core™ i7 11<sup>th</sup> Gen (Tiger Lake)
  - to 2.8 GHz w/ 4 Cores & 12M Smart Cache Integrated PCH-LP
- Up to 32 GB DDR4 SDRAM (16 GB default) In-band ECC memory
   Up to 512 GB SATA III SSD (256 GB default)
- Backup-boot NOR FLASH BIOS
- Video Display Port Output • Up to 7680 x 4320 @ 60 Hz
- Smart I/O Function
- Support for one independent smart module ٥
- Supports PCIe or SATA expansion modules e.g. ۰ EM1 for 2 additional Gig-E ports, or extended data storage FMx modules
- Background & Built-in-Test Support
- (as/if applicable)

- **COSA®** Architecture
- Motherboard Peripheral I/O • 2x 10/100/1000BASE-T Ethernet
  - 4x GPIO (TTL type) o
  - 2x Shared w/ I2C option
  - 1x Shared w/ Tamper option 1x Shared w/ UART#2
  - 2x RS-232 UART Ports
  - UART Port#1, front and rear
  - UART Port#2, optioned w/ TTL#4 and HDW\_WP 2x USB 2.0 Ports
- Security / Cybersecurity (Options)
- Up to FIPS 140-3 Level 3 Design Support o Crypto-key storage 0
- Battery-backed RAM
- (external supplied VBAT source) Secure Boot
- Tamper Detect & Erasure (pending)

- **Operating Systems Support**  Ubuntu 22.x Linux®
  - (for other OSes, contact factory) Intelligent I/O library support
- **Commercial or Rugged Applications**
- **Operating Temperature**  Commercial: 0°C to 55°C<sup>†</sup> Rugged: -40°C to 85°C
- Mechanical Options (ANSI/VITA 48) Air-cooled<sup>†</sup>: 3U, 4 HP (0.8" pitch)
  Conduction-cooled: 3U, 0.8" pitch
- Power
- 35 W Typical\* (no module power) ٥ \*Depending on number of Cores, Core Speed, DDR speed, OS, SW Application, etc



## Select 1 independent function for your application

I/O Modules										
Function	Module	Description	Function	Module	Description					
Analog-to-Digital	AD1	12 CH. A/D, ±10 V, Dedicated, 256 kHz (max), Sigma-Delta	Digital-to-Analog	<u>DA5</u>	4 CH. D/A, High-Voltage/High-Current Half-Bridge (2 Channels Full- Bridge) External VCC Sourced Outputs					
	AD2	12 CH. A/D, ±100 V (max), Dedicated, 256 kHz (max), Sigma-Delta	Dirite I.O. Differential Technologium	DF1	16 CH. Differential I/O, Input: -10 V to +10 V (422), -7 V to +12 V (485) Output:25 V to +5 V					
	AD3	12 CH. A/D, ±25 mA, Dedicated, 256 kHz (max), Sigma-Delta	Digital IO - Differential Transceiver	DF2	16 CH. 16 Channel Enhanced Differential I/O					
	AD4	16 CH. A/D, $\pm$ 10 V, Multiplexed, 500 KHz Agg / 8 Ch, SAR		DT1	24 CH. Discrete I/O, 0-60 VDC Input/Output, Max lout 500 mA - 2 A, Source/Sink (out)					
	<u>AD5</u>	16 CH. A/D, $\pm$ 50 V, Multiplexed, 500 KHz Agg / 8 Ch, SAR		DT2	16 CH. Discrete I/O, $\pm 80$ V Input/Output, Max lout 600 mA, Isolated/Ch Switch (out)					
	<u>AD6</u>	16 CH. A/D, $\pm$ 100 V, Multiplexed, 500 KHz Agg / 8 Ch, SAR	Discrete IO - Multichannel,Programmable	<u>DT3</u>	4 CH. Discrete Hi & Lo Side Switch Output @ 65V/2A (max), external individual supplied VCC & VSS per channel pair					
	<u>ADE</u>	16 CH. A/D, $\pm 10$ V, Individual 16-bit SAR, 200 kHz max., Simultaneous Sampling		DT4	24 CH. Enhanced DT1					
	<u>ADF</u>	16 CH. A/D, ±100 V, Individual 16-bit SAR, 200 kHz max., Simultaneous Sampling		<u>DT5</u>	16 CH. Enhanced DT2					
Chip Detector and Fuzz Burn	<u>CD1</u>	6 CH. Chip Detector (CD) and Fuzz Burn (FB)	Relay	<u>RY1</u>	4 CH. Relay, 220V/2A @ 60W/62.5VA (Max), Non Latching					
Digital-to-Analog	<u>DA1</u>	12 CH. D/A, $\pm$ 10 V, 25 mA Per Channel, Current or Voltage Control		<u>RY2</u>	4 CH. Relay, 220V/2A @ 60W/62.5VA (Max), Latching					
	<u>DA2</u>	16 CH. D/A, ± 10 V, 10 mA Per Channel, No Current Control	Digital IO - TTL.CMOS	<u>TL1</u>	24 CH. TTL I/O, Standard Functionality, Programmable					
	<u>DA3</u>	4 CH. D/A, ±40 V, ±100 mA, Voltage or Current Output	Digital IO - TTE, CINOS	<u>TL2</u>	24 CH. TTL I/O, Enhanced Functionality, Programmable					
	<u>DA4</u>	4 CH. D/A, $\pm$ 20 to $\pm$ 80, 10 mA, Voltage Control Only	Variable Reluctance	<u>VR1</u>	$8\mbox{ CH.}$ Variable Reluctance Signal Input and General-Purpose Pulse Counter, $\pm 100\mbox{ V},100\mbox{ kHz}$ (max)					
		Measure	ment & Simulation Modul	es						
Function	Module	Description	Function	Module	Description					
AC Reference	<u>AC2</u>	2 CH. AC Reference Source, 47 Hz - 20 KHz, ± 3% Acc, 2 – 28 Vrms, 6 VA (Max/Ch) Power	Synchro Resolver Measurement and Simulation	DSx (DRx)	1 - 3 CH. Digital to Synchro/Resolver, 2 - 90 VLL, 2 - 1115 Vrms Exc, 47 Hz - 20 kHz Freq					
	AC3	2 CH. AC Reference Source, 47 Hz - 2.5 KHz, ± 3% Acc, 28 – 115 Vrms, 6 VA (Max/Ch) Power	Pulse Timer Receiver and Generator	<u>PT1</u>	2 CH. Pulse Timer 1-PPS &/or 10 MHz Input with Multiple Outputs and 2 Channels Isolated RS-422/485 Serial Communications					
LVDT RVDT Measurement and Simulation	<u>DLx</u>	1 - 3 CH. Digital to LVDT/RVDT, 2 - 90 Vrms Full Scale, 2 - 115 Vrms Exc, 47 Hz - 20 kHz Freq	IRIG Timecode Receiver and Generator	<u>RG1</u>	1 CH. IRIG Timing Function Interface					
	LD1	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2- 115 Vrms Exc, 47 Hz -1 KHz Freq		<u>RT1</u>	8 CH. Resistance Temperature Detectors (RTD), 2, 3, or 4 wire, 16 Bit Res, 16.7 Hz/Ch					
	LD2	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2- 115 Vrms Exc, 1 KHz - 5 KHz Freq	Thermocouple and RTD Measurement	<u>TC1</u>	8 CH. Thermocouple, 4.17 - 470 Hz, ±100 mV A/D					
	LD3	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2- 115 Vrms Exc, 5 KHz - 10 KHz Freq		<u>TR1</u>	8 CH. Thermocouple (TCx) & Resistance Temperature Detectors (RTD), programmable per channel					
	<u>LD4</u>	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2- 115 Vrms Exc, 10 KHz - 20 KHz Freq	Strain Gauge Measurement	<u>SG1</u>	4 CH. Strain Gauge, 4.7 Hz - 4.8 KHz, Measurement, Conventional 4-Arm Bridge					
	<u>LD5</u>	4 CH. LVDT/RVDT to Digital, 28-90 Vrms Input, 2- 115 Vrms Exc, 47 Hz - 1 KHz Freq								



Communication Modules										
Function	Module	Description		Function	Module	Description				
ARINC Communications	<u>AR1</u>	12 CH. ARINC 429, 100 KHz or 12.5 KHz, RX/TX, 256 Word Tx/Rx Buffer		MIL-STD-1553B	<u>FTC</u>	4 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Transformer Coupled				
	AR2	1 CH. ARINC 568 (CH-1, RX & TX) & 1 Channel ARINC 579 (CH- 2, Programmable RX or TX), 1024-Word TX & RX Buffers per Ch.		MIL-STD-1760	<u>FTJ</u>	1 CH. MIL-STD-1760 (1553), BC, RT, BM, BM/RT, 128 KB RAM, Transformer Coupled				
CANBus Communications	<u>CB1</u>	8 CH. CANBus, CAN 2.0 A/B, 16 K RX/TX Buffer, 1 Mb/s Max Data Rate			<u>FTK</u>	2 CH. MIL-STD-1760 (1553), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Transformer Coupled				
	<u>CB2</u>	8 CH. CANBus, J1939, 16 K RX/TX Buffer, 500 kb/s Max Data Rate		IEEE 1394 (FireWire)	<u>FW3</u>	3 CH. (nodes), up to 3 ports per node, IEEE 1394b/AS5643 (Mil1394) (Firewire), S200b				
	<u>CB3</u>	8 CH. CANBus, CAN 2.0 A/B (CB1) or J1939 (CB2) protocol layer programmable per channel			SC3	8 CH. (max) RS-232/422/485 Serial Communications or GPIO, Programmable, Non-isolated				
Ethernet NIC Interface	EM1	2 CH. Dual Ethernet I/F, Intel 82850, 10/100/1000		Serial Communications	SC5	4 CH. RS-232/422/485 communications, isolated per channel and from SYS GND				
MIL-STD-1553B	<u>FTA</u>	1 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM, Transformer Coupled			SC6	4 CH. RS-232/422/485 communications, individual SYS GND provided per channel (non-isolated)				
	<u>FTB</u>	2 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Transformer Coupled		Time-Triggered Ethernet	<u>TE2</u>	3 CH. Single Channel, Tri-Redundant TTE/A664p7/AFDX/Best Effort End System				
Storage										
Function	Module	Description		Function	Module	Description				
SATA Solid State Drive (SSD)	<u>FM7</u>	1 CH. 1 TB SATA Flash, 3D NAND MLC, 0-70 °C operation		SATA Solid State Drive (SSD)	FM9	1 CH. 1.92 TB SATA TLC NAND Flash, Extended Temperature Operation				
	<u>FM8</u>	1 CH. 1 TB SATA TLC NAND Flash, Extended Temperature Operation								
Combination Modules										
Function	Module	Description		Function	Module	Description				
Combo	<u>CM5</u>	2 CH. Dual-redundant MIL-STD-1553 & 8 Channel ARINC 429/575, 100 KHz or 12.5 KHz, RX or TX, 256 Word Tx/Rx Buffer		Combo	<u>CM8</u>	2 CH. Dual-redundant MIL-STD-1553 & 12 Channel Discrete I/O, 0-60 VDC Input/Output, Max Iout 500 mA - 2 A, Source/Sink (out)				

### Architected for Versatility

NAI's Configurable Open Systems Architecture<sup>™</sup> (COSA®) offers a choice of over 100 smart I/O, communications, or Ethernet switch functions, providing the highest packaging density and greatest flexibility of ruggedized embedded product solutions in the industry. Preexisting, fully-tested functions can be combined in an unlimited number of ways quickly and easily.

#### **One-Source Efficiencies**

Eliminate man-months of integration with a configured, field-proven system from NAI. Specification to deployment is a seamless experience as all design, state-of-the-art manufacturing, assembly and test are performed - by one trusted source. All facilities are located within the U.S. and optimized for high-mix/low volume production runs and extended lifecycle support.

#### **Product Lifecycle Management**

From design to production and beyond, NAI's product lifecycle management strategy ensures the long-term availability of COTS products through configuration management, technology refresh and obsolescence component purchase and storage.



All specifications are subject to change without notice. All product and company names are trademarks or registered trademarks of their respective holders